



BOARD CHARACTERISTICS

Copper Layer Count: 4 Board Thickness: 1.7699 mm
Board overall dimensions: 31.6000 mm x 48.6000 mm
Min track/spacing: 0.1270 mm / 0.1270 mm Min hole diameter: 0.2540 mm
Copper Finish: None Impedance Control: No
Castellated pads: No Plated Board Edge: No
Edge card connectors: No

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.0254 mm	Purple	3.3	0
F.Cu	copper		0.04318 mm		1	0
Dielectric 1	prepreg	FR4	0.202184 mm		4.5	0.02
In1.Cu	copper		0.017272 mm		1	0
Dielectric 2	core	FR4	1.1938 mm		4.5	0.02
In2.Cu	copper		0.017272 mm		1	0
Dielectric 3	prepreg	FR4	0.202184 mm		4.5	0.02
B.Cu	copper		0.04318 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.0254 mm	Purple	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	White	1	0

HugonLabs

Sheet:
File: lna_sma_10x.kicad_pcb

Title: Low Noise Amplifier SMA 10x

Size: USLetter Date: 2022-03-10
KiCad E.D.A. kicad 6.0.2-378541a8eb-116-ubuntu20.04.1

Rev: 1.0
Id: 1/1